ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INDUSTRIES®	<ol><li>IPC. Bannockl</li></ol>	ourn. Illinois. A	ll rights reserved untions.	Inder both This do level pa	ocument arts, the	is a declaration er	on of the su	ibstances s all lowe	within the manufac r level materials for	turer listed which the	l item. Not manufacti	te: if the i urer has e	item is an assen engineering resp	bly with lower oonsibility.
				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				erials and	als and Mfg Information				
Supplier Information														
Company name*	Company unique ID			Un	Unique ID Authority					Response Date*				
onsemi Contact Name				DL						2023-06-08				
Product-Env-Stewards					Phone - Contact* NA					Email - Contact* Product-Env-Stewards@onsemi.com				
Authorized Representative*	Title - Representative			Ph	Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewards	Product Enviro Compliance			NA	NA				Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	n Number	Mfr Item Name		Ef	ffective Date	Version	I	Manufacturing Site		Weight*	τ	UOM	Unit Type
	NCP115	NCP115ASN150T2G 300 mA CMOS Lo AD; TSOP5		ow Dropout Regulator	V5 2023-06-08			(	CN1		13.65	I	mg	Each
Manufacturing Proccess Inform	nation													
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base Allo		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature Max T		re Max Time at Pe	ak Temperature Number of Ref		Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	sec	onds 3			
Comments														
level 1 - maximum time at peak temper	rature during so	ldering is 10-3	0 seconds											
For more information regarding mate	ial composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material Weight		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.12	mg	Supplier	Silicon (Si)	7440-21-3		0.12	mg
Lead Frame	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.526	mg
			В	Nickel (Ni)	7440-02-0		2.127	mg
			Supplier	Iron (Fe)	7439-89-6		2.9189	mg
			Supplier	Copper (Cu)	7440-50-8		0.2081	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg